Operational Amplifier, Railto-Rail Output, 3 MHz BW

The NCx2007x series operational amplifiers provide rail–to–rail output operation, 3 MHz bandwidth, and are available in single, dual, and quad configurations. Rail–to–rail operation enables the user to make optimal use of the entire supply voltage range while taking advantage of 3 MHz bandwidth. The NCx2007x can operate on supply voltages as low as 2.7 V over the temperature range of –40°C to 125° C. At a 2.7 V supply, the high bandwidth provides a slew rate of 2.8 V/µs while only consuming 405 µA of quiescent current per channel. The wide supply range allows the NCx2007x to run on supply voltages as high as 36 V, making it ideal for a broad range of applications. Since this is a CMOS device, high input impedance and low bias currents make it ideal for interfacing to a wide variety of signal sensors. The NCx2007x devices are available in a variety of compact packages. Automotive qualified options are available under the NCV prefix.

Features

- Rail-To-Rail Output
- Wide Supply Range: 2.7 V to 36 V
- Wide Bandwidth: 3 MHz typical at $V_S = 2.7 \text{ V}$
- High Slew Rate: 2.8 V/ μ s typical at V_S = 2.7 V
- Low Supply Current: 405 μ A per channel at $V_S = 2.7 \text{ V}$
- Low Input Bias Current: 5 pA typical
- Wide Temperature Range: -40°C to 125°C
- Available in a variety of packages
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Current Sensing
- Signal Conditioning
- Automotive

End Products

- Notebook Computers
- Portable Instruments
- Power Supplies

This document contains information on some products that are still under development. ON Semiconductor reserves the right to change or discontinue these products without notice.



ON Semiconductor®

www.onsemi.com





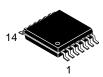
SOT-553 CASE 463B TSOP-5 CASE 483





Micro8[™] CASE 846A SOIC-8 CASE 751





TSSOP-8 CASE 948S

TSSOP-14 CASE 948G



SOIC-14 NB CASE 751A

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 2 of this data sheet.

ORDERING INFORMATION

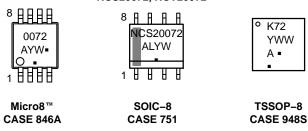
See detailed ordering and shipping information on page 4 of this data sheet.

MARKING DIAGRAMS

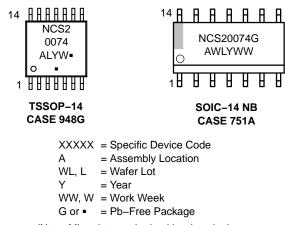
Single Channel Configuration NCS20071, NCV20071



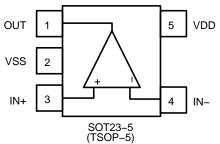
Dual Channel Configuration NCS20072, NCV20072

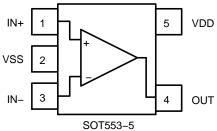


Quad Channel Configuration NCS20074, NCV20074

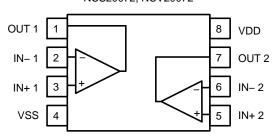


Single Channel Configuration NCS20071, NCV20071





Dual Channel Configuration NCS20072, NCV20072



Quadruple Channel Configuration NCS20074, NCV20074

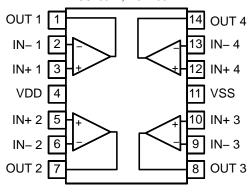


Figure 1. Pin Connections

ORDERING INFORMATION

Device	Configuration	Automotive	Marking	Package	Shipping [†]
NCS20071SN2T1G		No	AEA	TSOP-5 (Pb-Free)	3000 / Tape and Reel
NCS20071XV53T2G (In Development)**	Otracla	No	AL	SOT553-5 (Pb-Free)	4000 / Tape and Reel
NCV20071SN2T1G*	Single	Va a	AEA	TSOP-5 (Pb-Free)	3000 / Tape and Reel
NCV20071XV53T2G* (In Development)**		Yes	AL	SOT553-5 (Pb-Free)	4000 / Tape and Reel
NCS20072DMR2G			0072	Micro8 (MSOP8) (Pb-Free)	4000 / Tape and Reel
NCS20072DR2G		No	NCS20072	SOIC-8 (Pb-Free)	2500 / Tape and Reel
NCS20072DTBR2G			K72	TSSOP-8 (Pb-Free)	2500 / Tape and Reel
NCV20072DMR2G*	Dual		0072	Micro8 (MSOP8) (Pb-Free)	4000 / Tape and Reel
NCV20072DR2G*		Yes	NCS20072	SOIC-8 (Pb-Free)	2500 / Tape and Reel
NCV20072DTBR2G*			K72	TSSOP-8 (Pb-Free)	2500 / Tape and Reel
NCS20074DR2G			NCS20074	SOIC-14 (Pb-Free)	2500 / Tape and Reel
NCS20074DTBR2G	Overl	No	NCS2 0074	TSSOP-14 (Pb-Free)	2500 / Tape and Reel
NCV20074DR2G*	Quad	Vi s	NCS20074	SOIC-14 (Pb-Free)	2500 / Tape and Reel
NCV20074DTBR2G*		Yes	NCS2 0074	TSSOP-14 (Pb-Free)	2500 / Tape and Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP

Capable.

^{**}Contact local sales office for availability.

ABSOLUTE MAXIMUM RATINGS (Note 1)

	Rating	Symbol	Limit	Unit	
Supply Voltage (V _{DD} – V _{SS}) (Note 4)	Vs	40	V	
Input Voltage		V _{CM}	$V_{SS} - 0.2$ to $V_{DD} + 0.2$	V	
Differential Input Voltage (N	lote 2)	V_{ID} $\pm V_{S}$			
Maximum Input Current		I _{IN}	±10	mA	
Maximum Output Current (Note 3)	I _O	±100	mA	
Continuous Total Power Dis	ssipation (Note 4)	P_{D}	200	mW	
Maximum Junction Temper	ature	T_J	150	°C	
Storage Temperature Rang	e	T _{STG}	-65 to 150	°C	
Mounting Temperature (Infi	rared or Convection – 20 sec)	T _{mount}	260	°C	
ESD Capability (Note 5)	Human Body Model Machine Model – NCx20071 Machine Model – NCx20072, NCx20074 Charged Device Model – NCx20071, NCx20072 Charged Device Model – NCx20074	HBM MM MM CDM CDM	2000 200 150 2000 (C6) 1000 (C6)	V	
Latch-Up Current (Note 6)		I _{LU}	100	mA	
Moisture Sensitivity Level (Note 7)	MSL	Level 1		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
- 2. Maximum input current must be limited to ±10 mA. Series connected resistors of at least 500 Ω on both inputs may be used to limit the maximum input current to ±10 mA.
- 3. Total power dissipation must be limited to prevent the junction temperature from exceeding the 150°C limit.
- 4. Continuous short circuit operation to ground at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of the maximum output current rating over the long term may adversely affect reliability. Shorting output to either VDD or VSS will adversely affect reliability.
- 5. This device series incorporates ESD protection and is tested by the following methods:
 - ESD Human Body Model tested per JEDEC standard JS-001 (AEC-Q100-002)
 - ESD Machine Model tested per JEDEC standard JESD22-A115 (AEC-Q100-003)
 - ESD Charged Device Model tested per JEDEC standard JESD22-C101 (AEC-Q100-011)
- 6. Latch-up Current tested per JEDEC standard JESD78 (AEC-Q100-004)
- 7. Moisture Sensitivity Level tested per IPC/JEDEC standard J-STD-020A

THERMAL INFORMATION

Parameter	Symbol	Package	Single Layer Board (Note 8)	Multi–Layer Board (Note 9)	Unit	
		SOT23-5 / TSOP5	265	195		
		SOT553-5	325	244		
	$\theta_{ extsf{JA}}$	Micro8 / MSOP8	236	167		
Junction-to-Ambient		SOIC-8	190	131	°C/W	
		TSSOP-8	253	194		
		SOIC-14	142	101		
		TSSOP-14	179	128	1	

- 8. Values based on a 1S standard PCB according to JEDEC51-3 with 1.0 oz copper and a 300 mm² copper area
- 9. Values based on a 1S2P standard PCB according to JEDEC51-7 with 1.0 oz copper and a 100 mm² copper area

OPERATING RANGES

Parameter	Symbol	Min	Max	Unit
Operating Supply Voltage (Single Supply)	Vs	2.7	36	V
Operating Supply Voltage (Split Supply)	Vs	±1.35	±18	V
Differential Input Voltage (Note 10)	V_{ID}		V _S	V
Input Common Mode Voltage Range	V _{CM}	V _{SS}	V _{DD} – 1.35	V
Ambient Temperature	T _A	-40	125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

10. Maximum input current must be limited to ± 10 mA. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 2.7 V $T_A = 25^{\circ}\text{C}$; $R_L \ge 10$ kΩ; $V_{CM} = V_{OUT} = \text{mid}$ –supply unless otherwise noted. All limits are guaranteed by testing or statistical analysis. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 11, 12)

Parameter	Symbol	Cond	litions	Min	Тур	Max	Unit
INPUT CHARACTERISTICS							
		NCv	20071		1.3	±3.5	
Input Offset Valtage	V	NCX.	20071			±4.5	mV
Input Offset Voltage	Vos	NCv20072	NCv20074		1.3	±3	IIIV
		NCX20072	, NCx20074			±4	
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	T _A = 25°0	C to 125°C		2		μV/°C
Input Bias Current (Note 12)	L.				5	200	nΛ
Input Bias Current (Note 12)	I _{IB}					1500	pА
		NCv20071	NCv20072		2	75	
Input Officet Current (Note 42)		NCX20071	NCx20071, NCx20072			500	pА
Input Offset Current (Note 12)	I _{OS}	NOv	20074		2	75	рА
		NCX.	NCx20074			200	
Channel Conserving	VTLK	DC	NCx20072		100		dB
Channel Separation	XTLK	DC NCx20074			115		dB
Differential Input Resistance	R _{ID}				5		GΩ
Common Mode Input Resistance	R _{IN}				5		GΩ
Differential Input Capacitance	C _{ID}				1.5		pF
Common Mode Input Capacitance	C _{CM}				3.5		pF
0 11 5 : 5	OMBB	., ., .,	V/ V/ 4.05.V/	90	110		
Common Mode Rejection Ratio	CMRR $V_{CM} = V_{SS} + 0.2 \text{ V to } V_{DD} - 1.35 \text{ V}$		v to v _{DD} – 1.35 v	69			- dB
OUTPUT CHARACTERISTICS							
0	^			96	118		-in
Open Loop Voltage Gain	A_{VOL}		Ī	86			dB
0 0		Op amp sir	nking current		70		
Output Current Capability (Note 13)	I _O	Op amp sou	rcing current		50		mA
0					0.006	0.15	.,
Output Voltage High	V _{OH}	Voltage output swi	ng from positive rail			0.22	V
	.,				0.005	0.15	.,
Output Voltage Low	V_{OL}	Voltage output swir	ng from negative rail			0.22	V
AC CHARACTERISTICS							
Unity Gain Bandwidth	UGBW	C _L = 25 pF			3		MHz
Slew Rate at Unity Gain	SR	$C_{L} = 20 \text{ pF}$	$R_L = 2 k\Omega$		2.8		V/μs
Phase Margin	φm	C _L =	25 pF		50		٥
Gain Margin	A _m	C _L =	25 pF		14		dB
		$V_{O} = 1 \text{ Vpp},$	Settling time to 0.1%		0.6		
Settling Time	t _S G	Gain = 1, C_L = 20 pF Settling time to 0.01%			1.2		μS

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{11.} Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.

^{12.} Performance guaranteed over the indicated operating temperature range by design and/or characterization.

^{13.} Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 2.7 V

 $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid}$ –supply unless otherwise noted. All limits are guaranteed by testing or statistical analysis. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 11, 12)

Parameter	Symbol	Cond	itions	Min	Тур	Max	Unit
NOISE CHARACTERISTICS							
Total Harmonic Distortion plus Noise	THD+N	V _{IN} = 0.5 Vpp, f	V _{IN} = 0.5 Vpp, f = 1 kHz, Av = 1				%
Inner Deferred Valters Naise	f = 1 kHz		kHz		30		->///
Input Referred Voltage Noise	e _n	f = 10 kHz			20		nV/√ Hz
Input Referred Current Noise	i _n	f = 1 kHz			90		fA/√ Hz
SUPPLY CHARACTERISTICS							
Davisa Comple Daiostica Datia	2022	No. 1		114	135		-10
Power Supply Rejection Ratio	PSRR	NO L	_oad	100			dB
		NC20074	Noteed		420	625	
D		NCx20071	No load			765	_
Power Supply Quiescent Current	I _{DD} -		Dan dia sanda a dan d		405	525	μΑ
		NCx20072, NCx20074 Per channel, no load				625	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 11. Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.
- 12. Performance guaranteed over the indicated operating temperature range by design and/or characterization.
- 13. Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 5 V

 $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise noted. All limits are guaranteed by testing or statistical analysis. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 14, 15)

Parameter	Symbol	С	onditions	Min	Тур	Max	Unit
INPUT CHARACTERISTICS							
			1000074		1.3	±3.5	
Innut Offact Valtage	\/	r	ICx20071			±4.5	\/
Input Offset Voltage	Vos	NC20	070 NO. 00074		1.3	±3	mV
		NCx20072, NCx20074				±4	1
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	$T_A = 2$	25°C to 125 °C		2		μV/°C
Input Bias Current (Note 15)					5	200	π Λ
input bias Current (Note 15)	I _{IB}					1500	pА
		NCx20071, NCx20072			2	75	
land Offert Comment (Nets 45)	1					500	π Λ
Input Offset Current (Note 15)	los		1000074		2	75	- pA
		r	ICx20074			200	
Ohana al Oaranatia a	VTLK	D0	NCx20072		100		.ID
Channel Separation	XTLK	DC	NCx20074		115		dB
Differential Input Resistance	R _{ID}		•		5		GΩ
Common Mode Input Resistance	R _{IN}				5		GΩ
Differential Input Capacitance	C _{ID}				1.5		pF
Common Mode Input Capacitance	C _{CM}				3.5		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 14. Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.
- 15. Performance guaranteed over the indicated operating temperature range by design and/or characterization.
- 16. Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 5 V $T_A = 25^{\circ}C$; $R_L \ge 10$ kΩ; $V_{CM} = V_{OUT} = \text{mid}$ –supply unless otherwise noted. All limits are guaranteed by testing or statistical analysis. **Boldface** limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to 125°C. (Notes 14, 15)

Parameter	Symbol	Cond	itions	Min	Тур	Max	Unit
INPUT CHARACTERISTICS							
0 11 5 : 5	OMBB	, , , , , , , , , , , , , , , , , , ,	V. V. 4.05.V.	102	125		i.
Common Mode Rejection Ratio	CMRR	$V_{CM} = V_{SS} + 0.2$	V to V _{DD} – 1.35 V	80			- dB
OUTPUT CHARACTERISTICS		•					
On an Loan Voltage Cain	٨			96	120		15
Open Loop Voltage Gain	A_{VOL}			86			dB
Output Current Conchility (Note 16)	,	Op amp sin	king current		50		A
Output Current Capability (Note 16)	I _O	Op amp sou	rcing current		60		mA
Output Voltage High	V	Voltage output out	a a from positive roil		0.013	0.20	V
Output Voltage High	V _{OH}	Voltage output swing from positive rail				0.25	·
Output Voltage Low	V	Voltago output owin	og from pogotivo roil		0.01	0.10	V
Output Voltage Low	V _{OL}	voltage output swir	ng from negative rail			0.15	V
AC CHARACTERISTICS							
Unity Gain Bandwidth	UGBW	C _L =	25 pF		3		MHz
Slew Rate at Unity Gain	SR	$C_{L} = 20 \text{ pF}$	$R_L = 2 k\Omega$		2.7		V/μs
Phase Margin	ϕ_{m}	C _L =	25 pF		50		٥
Gain Margin	A_{m}	C _L =	25 pF		14		dB
Comilia a Timo o		$V_{O} = 3 \text{ Vpp},$ Gain = 1, $C_{L} = 20 \text{ pF}$	Settling time to 0.1%		1.2		
Settling Time	t _S	Gain = 1, $C_L = 20 \text{ pF}$	Settling time to 0.01%		5.6		μs
NOISE CHARACTERISTICS							
Total Harmonic Distortion plus Noise	THD+N	V _{IN} = 2.5 Vpp, f	= 1 kHz, Av = 1		0.009		%
Innuit Defermed Valteria Naina	_	f = 1	kHz		30		nV/√ Hz
Input Referred Voltage Noise	e _n	f = 10) kHz		20		11V/VIIZ
Input Referred Current Noise	i _n	f = 1	kHz		90		fA/√ Hz
SUPPLY CHARACTERISTICS							
5 0 15: " 5"	2022			114	135		i.
Power Supply Rejection Ratio	PSRR	No Load		100			dB
		NC-20074	Noteed		430	635	1
Davier Comply Ordensest Ormers		NCx20071	No load			775	
Power Supply Quiescent Current	I _{DD}	NOv20072 NOv20074 D	Development and and		410	530	μΑ
		NCx20072, NCx20074 Per channel, no load				630	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{14.} Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.

^{15.} Performance guaranteed over the indicated operating temperature range by design and/or characterization.

^{16.} Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT $V_S = 10 \text{ V}$

 $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid}$ –supply unless otherwise noted. All limits are guaranteed by testing or statistical analysis. Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 17, 18)

Parameter	Symbol	Cond	itions	Min	Тур	Max	Unit
INPUT CHARACTERISTICS							
Innut Officet Vallege	N/	NOve	20074		1.3	±3.5	mV
Input Offset Voltage	V _{OS}	NCX2	20071			±4.5	mV
Input Offset Voltage	V	NCv20072	NCx20074		1.3	±3	mV
input Onset voltage	V _{OS}	NOX20072	110220074			±4	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	T _A = 25°C	to 125°C		2		μV/°C
Input Bias Current (Note 18)	I _{IB}				5	200	рA
	.10					1500	μ, .
		NCx20071.	NCx20072		2	75	
Input Offset Current (Note 18)	I _{OS}					500	рА
put Gilber Guirein (i tete 16)	.03	NCx	20074		2	75	
						200	
Channel Separation	XTLK	DC	DC NCx20072		100		dB
	XILK	20	NCx20074		115		4.5
Differential Input Resistance	R _{ID}				5		GΩ
Common Mode Input Resistance	R _{IN}				5		GΩ
Differential Input Capacitance	C _{ID}				1.5		pF
Common Mode Input Capacitance	C _{CM}				3.5		pF
Common Mode Rejection Ratio	CMRR	Von = Voc + 0.2	V to V _{DD} – 1.35 V	110	130		dB
Common Mode Rejection ratio	Omar	VCIVI — VSS 1 0.2	* to *DD * 1.00 *	87			(I)
OUTPUT CHARACTERISTICS					_		
Open Loop Voltage Gain	A _{VOL}			98	120		dB
	, vol			88			4.5
Output Current Capability (Note 19)	I _O	Op amp sin	king current		50		mA
Catput Carrent Capability (140to 15)	10	Op amp sou	rcing current		65		1117.
Output Voltage High	V _{OH}	Voltage output swi	ng from positive rail		0.023	0.08	V
- Calput Voltage Flight	VОН	voltage output swii	ig irom poolave raii			0.10	V
Output Voltage Low	V _{OL}	Voltage output swir	ng from negative rail		0.022	0.3	V
- Catput Voltage Low	VOL	voltage output swii	ig irom riegative raii			0.35	·
AC CHARACTERISTICS							
Unity Gain Bandwidth	UGBW	C _L =	25 pF		3		MHz
Slew Rate at Unity Gain	SR	$C_{L} = 20 \text{ pF}$	$R_L = 2 k\Omega$		2.6		V/μs
Phase Margin	ϕ_{m}	C _L =	25 pF		50		٥
Gain Margin	A _m	C _L =	25 pF		14		dB
Settling Time	to	$V_{O} = 8.5 \text{ Vpp},$	Settling time to 0.1%		3.4		li 6
Committee of the commit	t _S G	Gain = 1, $C_L = 20 \text{ pF}$	Settling time to 0.01%		6.8	μS	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{17.} Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.

^{18.} Performance guaranteed over the indicated operating temperature range by design and/or characterization.

^{19.} Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 10 V

 $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise noted. All limits are guaranteed by testing or statistical analysis. Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 17, 18)

Parameter	Symbol	Cond	itions	Min	Тур	Max	Unit
NOISE CHARACTERISTICS							
Total Harmonic Distortion plus Noise	THD+N	V _{IN} = 7.5 Vpp, f	V _{IN} = 7.5 Vpp, f = 1 kHz, Av = 1				%
Inner Defermed Voltage Naise	f = 1 kHz		f = 1 kHz		30		->///
Input Referred Voltage Noise	e _n	f = 10 kHz			20		nV/√ Hz
Input Referred Current Noise	i _n	f = 1 kHz			90		fA/√ Hz
SUPPLY CHARACTERISTICS							
Davisa Comple Daiostica Datia	2022			114	135		-10
Power Supply Rejection Ratio	PSRR	NO L	_oad	100			dB
		NC20074	Noteed		430	645	
D		NCx20071	No load			785	1 ,
Power Supply Quiescent Current	I _{DD}		Day shawasi wa laad		416	540	μΑ
		NCx20072, NCx20074 Per channel, no load				640	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 17. Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.
- 18. Performance guaranteed over the indicated operating temperature range by design and/or characterization.
- 19. Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 36 V

 $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise noted. All limits are guaranteed by testing or statistical analysis. Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 20, 21)

Parameter	Symbol	Con	ditions	Min	Тур	Max	Unit
INPUT CHARACTERISTICS							
		NCx20071			1.3	±3.5	mV
land Office Valtage	V _{OS}	NC)	(20071			±4.5	mV
Input Offset Voltage		NCv2007	0. NCv20074		1.3	±3	mV
		NCX2007.	NCx20072, NCx20074			±4	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$	$T_A = 25^{\circ}$	°C to 125°C		2		μV/°C
					5	200	
Input Bias Current (Note 21)	I _{IB}	NCx20071, NCx20072				2000	рА
		NC:			1500		
		NCv2007	NCx20071, NCx20072		2	75	
Innut Offert Comment (Nata 24)		NCX2007				1000	
Input Offset Current (Note 21)	los	NO	.00074		2	75	- pA
		NC)	k20074			200	
Channel Consention	VTLK	DC.	NCx20072		100		40
Channel Separation	XTLK	DC NC	NCx20074		115		dB
Differential Input Resistance	R _{ID}				5		GΩ
Common Mode Input Resistance	R _{IN}				5		GΩ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 20. Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.
- 21. Performance guaranteed over the indicated operating temperature range by design and/or characterization.
- 22. Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 36 V $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid}$ –supply unless otherwise noted. All limits are guaranteed by testing or statistical analysis. Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 20, 21)

Parameter	Symbol	Cond	litions	Min	Тур	Max	Unit
INPUT CHARACTERISTICS		•	<u>, , , , , , , , , , , , , , , , , , , </u>				•
Differential Input Capacitance	C _{ID}				1.5		pF
Common Mode Input Capacitance	C _{CM}				3.5		pF
			$V_{CM} = V_{CC} + 0.2 \text{ V to}$	118	135		
		NCx20071	$V_{CM} = V_{SS} + 0.2 \text{ V to}$ $V_{DD} - 1.35 \text{ V}$	95			
			$V_{CM} = V_{SS} + 0.2 \text{ V to}$ $V_{DD} - 1.35 \text{ V}$	120	145		
Common Mode Rejection Ratio	CMRR	NCx20072		95			dB
			$V_{CM} = V_{SS} + 0.2 \text{ V to}$	120	145		1
		NCx20074	V _{DD} – 1.35 V	85			1
OUTPUT CHARACTERISTICS							
Open Lean Veltage Coin			98	120		JD	
Open Loop Voltage Gain	A_{VOL}	Ī		88			dB
0 0		Op amp sinking current			50		
Output Current Capability (Note 22)	Current Capability (Note 22) I _O Op amp sourcing current		rcing current		65		mA
			NO 00074		0.074	0.15	
Output Voltage High			NCx20071			0.22	- - - -
		Voltage output swing	NO 00070		0.074	0.10	
	V_{OH}	from positive rail	NCx20072			0.15	
			NCx20074		0.074	0.10	
						0.12	
0	.,				0.065	0.3	Ţ.,
Output Voltage Low	V_{OL}	Voltage output swir	ng from negative rail			0.35	V
AC CHARACTERISTICS			<u>.</u>				
Unity Gain Bandwidth	UGBW	C _L =	25 pF		3		MHz
Slew Rate at Unity Gain	SR	$C_{L} = 20 \text{ pF}$	$R_L = 2 k\Omega$		2.4		V/μs
Phase Margin	ϕ_{m}	C _L =	25 pF		50		0
Gain Margin	A _m	C _L =	25 pF		14		dB
Cottling Times		V _O = 10 Vpp,	Settling time to 0.1%		3.2		
Settling Time	t _S	Gain = 1, $C_L = 20 \text{ pF}$	Settling time to 0.01%		7		μS
NOISE CHARACTERISTICS							
Total Harmonic Distortion plus Noise	THD+N	V _{IN} = 28.5 Vpp,	f = 1 kHz, Av = 1		0.001		%
Input Poforred Voltage Noise	-	f = 1	kHz		30		nV/√ H z
Input Referred Voltage Noise	e _n	f = 1	0 kHz		20		11V/ VH2
Input Referred Current Noise	i _n	f = 1	kHz		90		fA/√Hz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{20.} Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.

^{21.} Performance guaranteed over the indicated operating temperature range by design and/or characterization.

^{22.} Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

ELECTRICAL CHARACTERISTICS AT V_S = 36 V $T_A = 25^{\circ}\text{C}$; $R_L \ge 10 \text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid}$ –supply unless otherwise noted. All limits are guaranteed by testing or statistical analysis. Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}\text{C}$ to 125°C. (Notes 20, 21)

Parameter	Symbol	Conditions		Min	Тур	Max	Unit		
SUPPLY CHARACTERISTICS									
Dawar Cumply Dejection Datio	DCDD	Noticed		114	135		٩D		
Power Supply Rejection Ratio PSRR		No Load		100			dB		
	NO. 20074	NI- I I		480	700				
		NCx20071	No load			840			
Dower Cumply Ouisesent Current			Dan ahammal na laad		465	570	^		
Power Supply Quiescent Current	I _{DD} NCx20072	Per channel, no load			700	μΑ			
		NCx20074	Der channel no load		465	600			
			Per channel, no load			700			

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 20. Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.
- 21. Performance guaranteed over the indicated operating temperature range by design and/or characterization.
- 22. Power dissipation must be limited to prevent junction temperature from exceeding 150°C. See Absolute Maximum Ratings for more information.

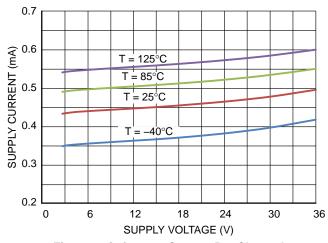


Figure 2. Quiescent Current Per Channel vs. Supply Voltage

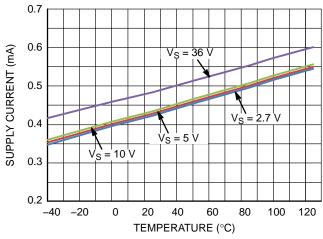


Figure 3. Quiescent Current vs. Temperature

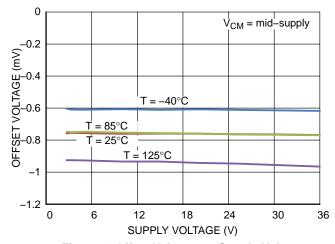


Figure 4. Offset Voltage vs. Supply Voltage

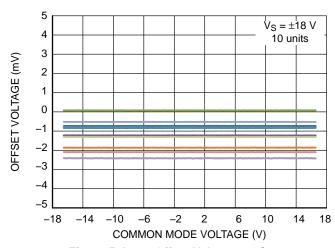


Figure 5. Input Offset Voltage vs. Common Mode Voltage

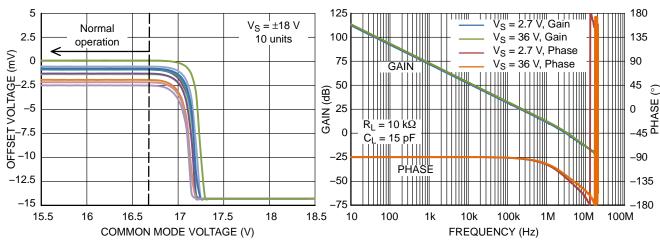


Figure 6. Input Offset Voltage vs. Common Mode Voltage

Figure 7. Gain and Phase vs. Frequency

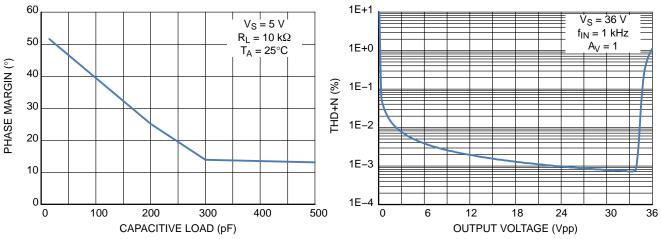


Figure 8. Phase Margin vs. Capacitive Load

Figure 9. THD+N vs. Output Voltage

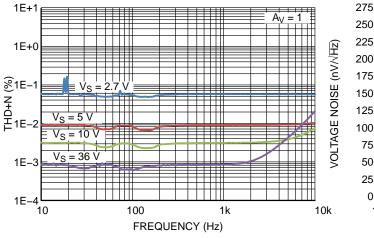


Figure 10. THD+N vs. Frequency

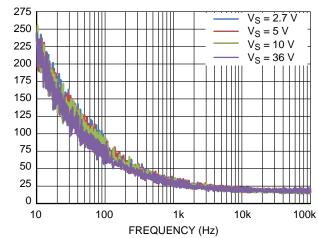


Figure 11. Input Voltage Noise vs. Frequency

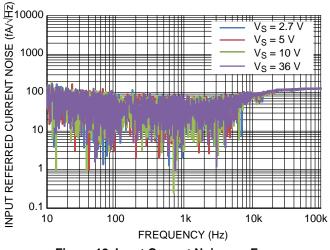


Figure 12. Input Current Noise vs. Frequency

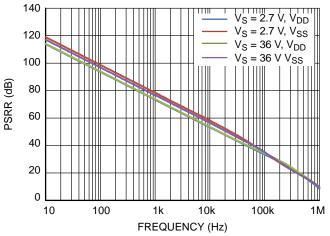
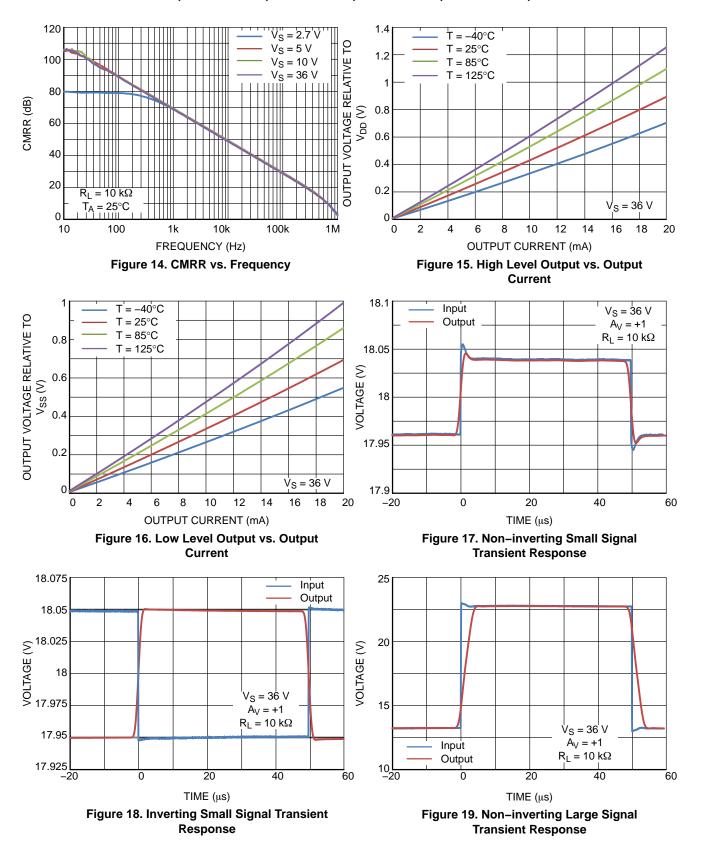


Figure 13. PSRR vs. Frequency



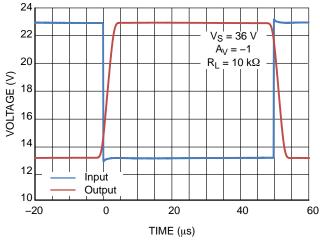


Figure 20. Inverting Large Signal Transient Response

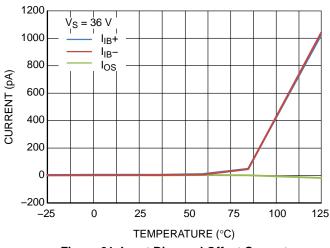


Figure 21. Input Bias and Offset Current vs.
Temperature

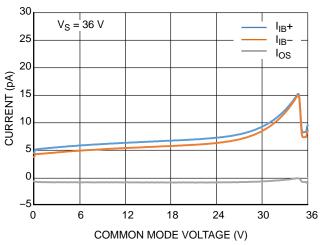


Figure 22. Input Bias Current vs. Common Mode Voltage

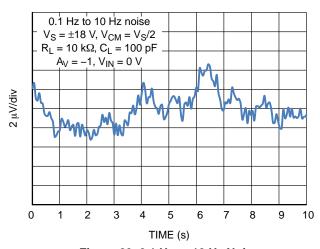


Figure 23. 0.1 Hz to 10 Hz Noise

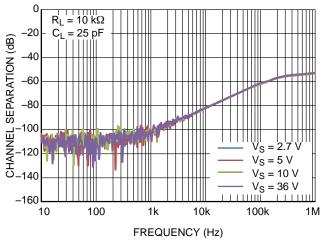


Figure 24. Channel Separation vs. Frequency

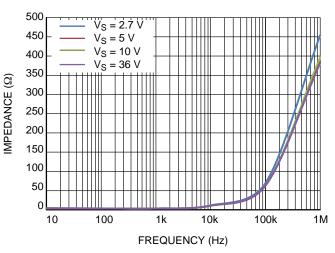
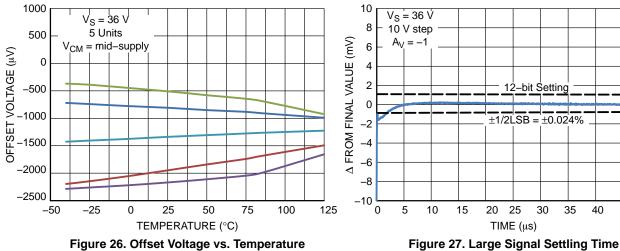


Figure 25. Open Loop Output Impedance



TIME (µs)

 $\pm 1/2$ LSB = $\pm 0.024\%$

Figure 26. Offset Voltage vs. Temperature

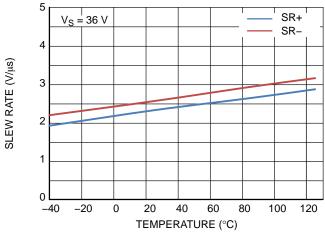


Figure 28. Slew Rate vs. Temperature

APPLICATIONS INFORMATION

Input Circuit

The NCS2007x input stage has a PMOS input pair and ESD protection diodes. The input pair is internally connected by back–to–back Zener diodes with a reverse voltage of 5.5 V. To protect the internal circuitry, the input current must be limited to 10 mA. When operating the

NCS2007x at differential voltages greater than $V_{ID}=26~V$, series resistors can be added externally to limit the input current flowing between the input pins. Adding 500 Ω resistors in series with the input prevents the current from exceeding 10 mA over the entire operating range up to 36 V.

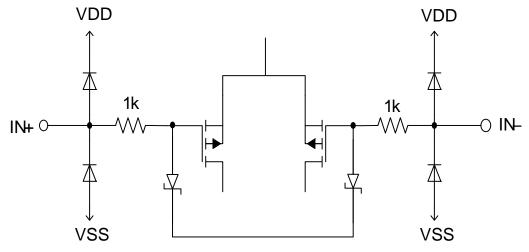


Figure 29. Differential Input Pair

Output

The NCS2007x has a class AB output stage with rail-to-rail output swing.

High output currents can cause the junction temperature to exceed the 150°C absolute maximum rating. In the case of a short circuit where the output is connected to either supply rail, the amount of current the op amp can source and sink is described by the output current capability parameter

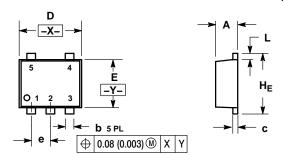
listed in the Electrical Characteristics. The junction temperature at a given power dissipation, P, can be calculated using the following formula:

$$T_J = T_A + P \; x \; \theta_{JA}$$

The thermal resistance between junction and ambient, θ_{JA} , is provided in the Thermal Information section of this datasheet.

PACKAGE DIMENSIONS

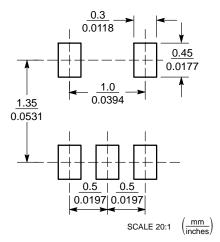
SOT-553, 5 LEAD CASE 463B ISSUE C



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
E	1.15	1.20	1.25	0.045	0.047	0.049
е		0.50 BSC		0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.55	1.60	1.65	0.061	0.063	0.065

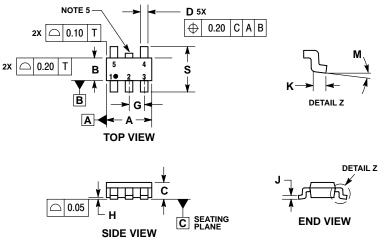
RECOMMENDED SOLDERING FOOTPRINT*



^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-5 CASE 483 ISSUE M

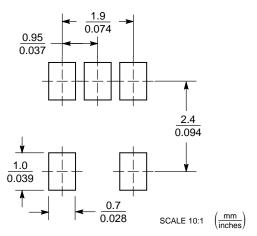


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
- 5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.85	3.15		
В	1.35	1.65		
С	0.90	1.10		
D	0.25	0.50		
G	0.95	BSC		
Н	0.01	0.10		
J	0.10	0.26		
K	0.20	0.60		
М	0°	10 °		
S	2.50	3.00		

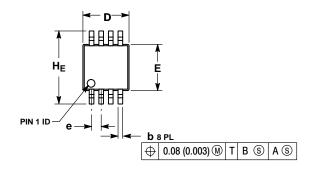
SOLDERING FOOTPRINT*

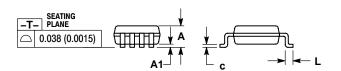


*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

Micro8™ CASE 846A-02 **ISSUE J**





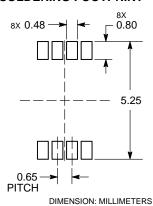
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE 3. DIMENSION A DUES NOT INCLUDE MOLLO FLASH, PHOTHOSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.06) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	М	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	-		1.10			0.043	
A1	0.05	0.08	0.15	0.002	0.003	0.006	
b	0.25	0.33	0.40	0.010	0.013	0.016	
С	0.13	0.18	0.23	0.005	0.007	0.009	
D	2.90	3.00	3.10	0.114	0.118	0.122	
E	2.90	3.00	3.10	0.114	0.118	0.122	
е		0.65 BSC		0.026 BSC			
L	0.40	0.55	0.70	0.016	0.021	0.028	
HE	4.75	4.90	5.05	0.187	0.193	0.199	

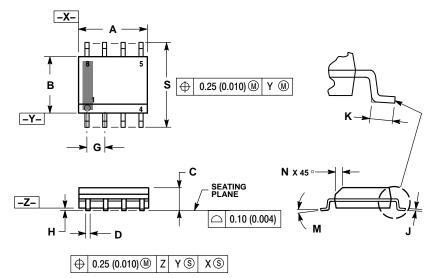
RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AK**

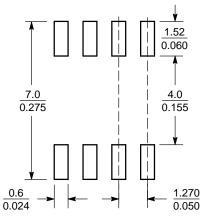


- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE

- MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW
- STANDARD IS 751-07.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
O	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
Κ	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

SOLDERING FOOTPRINT*

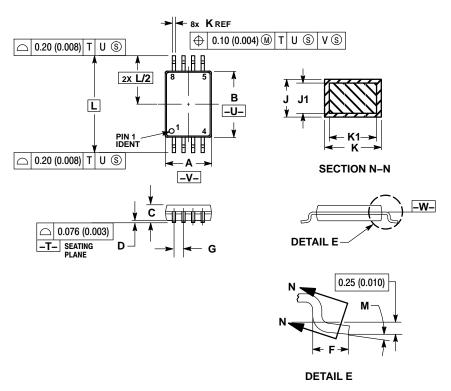


SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **CASE 948S** ISSUE C



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
- PER SIDE.

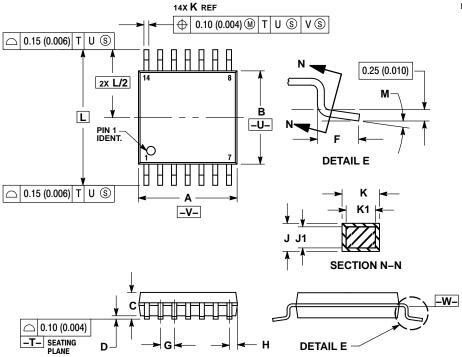
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	4.30	4.50	0.169	0.177	
С		1.10		0.043	
D	0.05	0.15	0.002	0.006	
F	0.50	0.70	0.020	0.028	
G	0.65	BSC	0.026 BSC		
ے	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40 BSC		0.252 BSC		
М	0°	8°	0°	8 0	

PACKAGE DIMENSIONS

TSSOP-14 CASE 948G ISSUE C



NOTES:

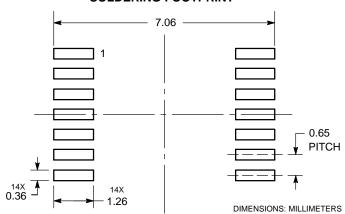
- DIMENSIONING AND TOLERANCING PER
 ANSLY 14 5M 1982
 - ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (DOE) PER SIDE
- EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR
- DIMENSION K DOES NOT INCLUDE DAMBAI PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

_					
	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65 BSC		0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
Г	6.40 BSC		0.252	BSC	
М	0°	8 °	0 °	8 °	

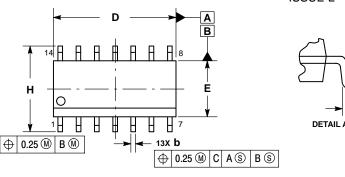
SOLDERING FOOTPRINT*



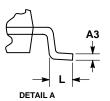
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

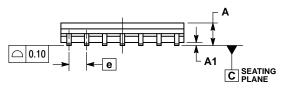
PACKAGE DIMENSIONS

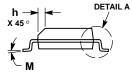
SOIC-14 NB CASE 751A-03 ISSUE L



14X





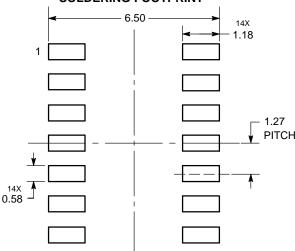


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
е	1.27	1.27 BSC		BSC
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
М	0 °	7°	0 °	7°

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Phone: 81–3–5817–1050